

Electronic Patent Application Fee Transmittal

Application Number:	10822961			
Filing Date:	13-Apr-2004			
Title of Invention:	MICROELECTRONICS PACKAGE ASSEMBLY TOOL AND METHOD OF MANUFACTURE THEREWITH			
First Named Inventor:	Chao-Yuan Su			
Filer:	David M. Odell/Denise Wilson			
Attorney Docket Number:	24061.59 (TSMC2003-0121)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1700